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KUO et al.(10) **Pub. No.: US 2024/0213067 A1**(43) **Pub. Date: Jun. 27, 2024**(54) **SEMICONDUCTOR FABRICATION SYSTEM
AND METHOD****Publication Classification**(71) Applicant: **Taiwan Semiconductor
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Jhubei City (TW)(21) Appl. No.: **18/601,423**(22) Filed: **Mar. 11, 2024****Related U.S. Application Data**(62) Division of application No. 16/939,820, filed on Jul.
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(57)

ABSTRACT

A system and computer-implemented method are provided for manufacturing a semiconductor electronic device. An assembler receives a jig and a boat supporting a die. The assembler includes a separator that separates the jig into a first jig portion and a second jig portion and a loader that positions the boat between the first jig portion and the second jig portion. A robot receives an assembly prepared by the assembler and manipulates a locking system that fixes an alignment of the boat relative to the first jig portion and the second jig portion to form a locked assembly. A process chamber receives the locked assembly and subjects the locked assembly to a fabrication operation.

